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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

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Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I ² C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	64KB (22K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep64mc204-e-pt

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Pin Diagrams (Continued)



2.5 ICSP Pins

The PGECx and PGEDx pins are used for ICSP and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes, and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin Voltage Input High (VIH) and Voltage Input Low (VIL) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB[®] PICkit[™] 3, MPLAB ICD 3, or MPLAB REAL ICE[™].

For more information on MPLAB ICD 2, ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

- "Using MPLAB[®] ICD 3" (poster) DS51765
- "MPLAB[®] ICD 3 Design Advisory" DS51764
- "MPLAB[®] REAL ICE[™] In-Circuit Emulator User's Guide" DS51616
- "Using MPLAB[®] REAL ICE™ In-Circuit Emulator" (poster) DS51749

2.6 External Oscillator Pins

Many DSCs have options for at least two oscillators: a high-frequency Primary Oscillator and a low-frequency Secondary Oscillator. For details, see **Section 9.0 "Oscillator Configuration"** for details.

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is shown in Figure 2-3.



SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT



FIGURE 2-5: SINGLE-PHASE SYNCHRONOUS BUCK CONVERTER







FIGURE 2-7: INTERLEAVED PFC





TABLE	4-Z:	CPU		EGISTEI	RIMAP		Z4EPX		C20X D	EVICES	ONLT							
File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
W0	0000								W0 (WR	EG)								xxxx
W1	0002								W1									xxxx
W2	0004								W2									xxxx
W3	0006								W3									xxxx
W4	8000								W4									xxxx
W5	000A								W5									xxxx
W6	000C								W6									xxxx
W7	000E								W7									xxxx
W8	0010								W8									xxxx
W9	0012								W9									xxxx
W10	0014								W10									xxxx
W11	0016								W11									xxxx
W12	0018								W12									xxxx
W13	001A								W13									xxxx
W14	001C								W14									xxxx
W15	001E								W15									xxxx
SPLIM	0020								SPLIM<1	5:0>								0000
PCL	002E			•			•	P	CL<15:1>								—	0000
PCH	0030	—	—	—	—	—	—		—	—				PCH<6:0>				0000
DSRPAG	0032	—	—	—	—	—	—					DSRPA	G<9:0>					0001
DSWPAG	0034	—	—	—	—	—	—	—				DS	SWPAG<8:0)>				0001
RCOUNT	0036			•			•		RCOUNT<	15:0>								0000
SR	0042	—	—		—	_	—	_	DC	IPL2	IPL1	IPL0	RA	N	OV	Z	С	0000
CORCON	0044	VAR	_	—	—	—	—	_	—	—	—	—	—	IPL3	SFA	—	—	0020
DISICNT	0052	—	DISICNT<13:0> 0000								0000							
TBLPAG	0054	—	—	—	—	—	—	—	—				TBLPA	G<7:0>				0000
MSTRPR	0058	MSTRPR<15:0> 0000																

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Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-59: PORTA REGISTER MAP FOR PIC24EPXXXGP/MC202 AND dsPIC33EPXXXGP/MC202/502 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISA	0E00		—	—				—			—		TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	001F
PORTA	0E02		—	_		_		—			—		RA4	RA3	RA2	RA1	RA0	0000
LATA	0E04		—	—				—			—		LATA4	LATA3	LATA2	LA1TA1	LA0TA0	0000
ODCA	0E06		—	—				—			—		ODCA4	ODCA3	ODCA2	ODCA1	ODCA0	0000
CNENA	0E08		—	—				—			—		CNIEA4	CNIEA3	CNIEA2	CNIEA1	CNIEA0	0000
CNPUA	0E0A		—	—				—			—		CNPUA4	CNPUA3	CNPUA2	CNPUA1	CNPUA0	0000
CNPDA	0E0C		—	—				—			—		CNPDA4	CNPDA3	CNPDA2	CNPDA1	CNPDA0	0000
ANSELA	0E0E	-	—	—			-	—		_	_		ANSA4	_	—	ANSA1	ANSA0	0013

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-60: PORTB REGISTER MAP FOR PIC24EPXXXGP/MC202 AND dsPIC33EPXXXGP/MC202/502 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISB	0E10	TRISB15	TRISB14	TRISB13	TRISB12	TRISB11	TRISB10	TRISB9	TRISB8	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	FFFF
PORTB	0E12	RB15	RB14	RB13	RB12	RB11	RB10	RB9	RB8	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx
LATB	0E14	LATB15	LATB14	LATB13	LATB12	LATB11	LATB10	LATB9	LATB8	LATB7	LATB6	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0	xxxx
ODCB	0E16	ODCB15	ODCB14	ODCB13	ODCB12	ODCB11	ODCB10	ODCB9	ODCB8	ODCB7	ODCB6	ODCB5	ODCB4	ODCB3	ODCB2	ODCB1	ODCB0	0000
CNENB	0E18	CNIEB15	CNIEB14	CNIEB13	CNIEB12	CNIEB11	CNIEB10	CNIEB9	CNIEB8	CNIEB7	CNIEB6	CNIEB5	CNIEB4	CNIEB3	CNIEB2	CNIEB1	CNIEB0	0000
CNPUB	0E1A	CNPUB15	CNPUB14	CNPUB13	CNPUB12	CNPUB11	CNPUB10	CNPUB9	CNPUB8	CNPUB7	CNPUB6	CNPUB5	CNPUB4	CNPUB3	CNPUB2	CNPUB1	CNPUB0	0000
CNPDB	0E1C	CNPDB15	CNPDB14	CNPDB13	CNPDB12	CNPDB11	CNPDB10	CNPDB9	CNPDB8	CNPDB7	CNPDB6	CNPDB5	CNPDB4	CNPDB3	CNPDB2	CNPDB1	CNPDB0	0000
ANSELB	0E1E			_	-	—	—	—	ANSB8		_	—		ANSB3	ANSB2	ANSB1	ANSB0	010F

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X AND PIC24EPXXXGP/MC20X

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0			
—	—	—		—	—	—				
bit 15							bit 8			
U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0			
		<u> </u>		RQCOL3	RQCOL2	RQCOL1	RQCOL0			
bit 7							bit 0			
Legend:										
R = Readable	bit	W = Writable	bit	U = Unimplemented bit, read as '0'						
-n = Value at I	POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkr	iown			
bit 15-4	Unimplemen	ted: Read as '	י)							
bit 3	RQCOL3: DM	IA Channel 3 T	ransfer Requ	est Collision Fl	lag bit					
	1 = User forc	e and interrupt	-based reques	st collision is d	etected					
	0 = No reque	est collision is d	etected							
bit 2	RQCOL2: DM	IA Channel 2 T	ransfer Requ	est Collision Fl	lag bit					
	1 = User forc	e and interrupt	-based reques	st collision is d	etected					
	0 = No reque	est collision is d	etected							
bit 1	RQCOL1: DM	1A Channel 1 T	ransfer Reque	est Collision Fl	lag bit					
	1 = User forc 0 = No reque	e and interrupt st collision is d	-based reques etected	st collision is d	etected					
bit 0	RQCOL0: DM	1A Channel 0 T	ransfer Requ	est Collision Fl	lag bit					
	1 = User forc	e and interrupt	-based reques	st collision is d	etected					

REGISTER 8-12: DMARQC: DMA REQUEST COLLISION STATUS REGISTER

0 = No request collision is detected

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X AND PIC24EPXXXGP/MC20X

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8
U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	TUN5	TUN4	TUN3	TUN2	TUN1	TUN0
bit 7							bit 0
I a manuali							

REGISTER 9-4: OSCTUN: FRC OSCILLATOR TUNING REGISTER

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit	, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-6 Unimplemented: Read as '0'

bit 5-0 **TUN<5:0>:** FRC Oscillator Tuning bits 011111 = Maximum frequency deviation of 1.453% (7.477 MHz) 011110 = Center frequency + 1.406% (7.474 MHz) •••• 000001 = Center frequency + 0.047% (7.373 MHz) 000000 = Center frequency (7.37 MHz nominal) 111111 = Center frequency - 0.047% (7.367 MHz) ••• 100001 = Center frequency - 1.453% (7.263 MHz) 100000 = Minimum frequency deviation of -1.5% (7.259 MHz)

11.5 I/O Helpful Tips

- 1. In some cases, certain pins, as defined in Table 30-11, under "Injection Current", have internal protection diodes to VDD and Vss. The term, "Injection Current", is also referred to as "Clamp Current". On designated pins, with sufficient external current-limiting precautions by the user, I/O pin input voltages are allowed to be greater or less than the data sheet absolute maximum ratings, with respect to the Vss and VDD supplies. Note that when the user application forward biases either of the high or low side internal input clamp diodes, that the resulting current being injected into the device, that is clamped internally by the VDD and Vss power rails, may affect the ADC accuracy by four to six counts.
- 2. I/O pins that are shared with any analog input pin (i.e., ANx) are always analog pins by default after any Reset. Consequently, configuring a pin as an analog input pin automatically disables the digital input pin buffer and any attempt to read the digital input level by reading PORTx or LATx will always return a '0', regardless of the digital logic level on the pin. To use a pin as a digital I/O pin on a shared ANx pin, the user application needs to configure the Analog Pin Configuration registers in the I/O ports module (i.e., ANSELx) by setting the appropriate bit that corresponds to that I/O port pin to a '0'.
- **Note:** Although it is not possible to use a digital input pin when its analog function is enabled, it is possible to use the digital I/O output function, TRISx = 0x0, while the analog function is also enabled. However, this is not recommended, particularly if the analog input is connected to an external analog voltage source, which would create signal contention between the analog signal and the output pin driver.
- 3. Most I/O pins have multiple functions. Referring to the device pin diagrams in this data sheet, the priorities of the functions allocated to any pins are indicated by reading the pin name from left-to-right. The left most function name takes precedence over any function to its right in the naming convention. For example: AN16/T2CK/T7CK/RC1. This indicates that AN16 is the highest priority in this example and will supersede all other functions to its right in the list. Those other functions to its right, even if enabled, would not work as long as any other function to its left was enabled. This rule applies to all of the functions listed for a given pin.
- 4. Each pin has an internal weak pull-up resistor and pull-down resistor that can be configured using the CNPUx and CNPDx registers, respectively. These resistors eliminate the need for external resistors in certain applications. The internal pull-up is up to ~(VDD - 0.8), not VDD. This value is still above the minimum VIH of CMOS and TTL devices.

5. When driving LEDs directly, the I/O pin can source or sink more current than what is specified in the VOH/IOH and VOL/IOL DC characteristic specification. The respective IOH and IOL current rating only applies to maintaining the corresponding output at or above the VOH, and at or below the VOL levels. However, for LEDs, unlike digital inputs of an externally connected device, they are not governed by the same minimum VIH/VIL levels. An I/O pin output can safely sink or source any current less than that listed in the absolute maximum rating section of this data sheet. For example:

VOH = 2.4V @ IOH = -8 mA and VDD = 3.3VThe maximum output current sourced by any 8 mA I/O pin = 12 mA.

LED source current < 12 mA is technically permitted. Refer to the VOH/IOH graphs in Section 30.0 "Electrical Characteristics" for additional information.

- 6. The Peripheral Pin Select (PPS) pin mapping rules are as follows:
 - a) Only one "output" function can be active on a given pin at any time, regardless if it is a dedicated or remappable function (one pin, one output).
 - b) It is possible to assign a "remappable output" function to multiple pins and externally short or tie them together for increased current drive.
 - c) If any "dedicated output" function is enabled on a pin, it will take precedence over any remappable "output" function.
 - d) If any "dedicated digital" (input or output) function is enabled on a pin, any number of "input" remappable functions can be mapped to the same pin.
 - e) If any "dedicated analog" function(s) are enabled on a given pin, "digital input(s)" of any kind will all be disabled, although a single "digital output", at the user's cautionary discretion, can be enabled and active as long as there is no signal contention with an external analog input signal. For example, it is possible for the ADC to convert the digital output logic level, or to toggle a digital output on a comparator or ADC input provided there is no external analog input, such as for a built-in self-test.
 - f) Any number of "input" remappable functions can be mapped to the same pin(s) at the same time, including to any pin with a single output from either a dedicated or remappable "output".

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X AND PIC24EPXXXGP/MC20X

REGISTER 16-8: PDCx: PWMx GENERATOR DUTY CYCLE REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			PDC	x<15:8>			
bit 15							bit 8
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			PDC	x<7:0>			
bit 7							bit 0
Legend:							
R = Readable	bit	W = Writable	bit	U = Unimpler	mented bit, rea	id as '0'	
-n = Value at P	OR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkr	nown

bit 15-0 **PDCx<15:0>:** PWMx Generator # Duty Cycle Value bits

REGISTER 16-9: PHASEx: PWMx PRIMARY PHASE-SHIFT REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			PHAS	Ex<15:8>			
bit 15							bit 8
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			PHAS	SEx<7:0>			
bit 7							bit 0
Legend:							
R = Readable I	bit	W = Writable b	it	U = Unimpler	mented bit, rea	ad as '0'	
-n = Value at P	OR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkı	nown

bit 15-0 PHASEx<15:0>: PWMx Phase-Shift Value or Independent Time Base Period for the PWM Generator bits

Note 1: If ITB (PWMCONx<9>) = 0, the following applies based on the mode of operation: Complementary, Redundant and Push-Pull Output mode (PMOD<1:0> (IOCON<11:10>) = 00, 01 or 10), PHASEx<15:0> = Phase-shift value for PWMxH and PWMxL outputs

 If ITB (PWMCONx<9>) = 1, the following applies based on the mode of operation: Complementary, Redundant and Push-Pull Output mode (PMOD<1:0> (IOCONx<11:10>) = 00, 01 or 10), PHASEx<15:0> = Independent time base period value for PWMxH and PWMxL

23.2 ADC Helpful Tips

- 1. The SMPIx control bits in the AD1CON2 register:
 - a) Determine when the ADC interrupt flag is set and an interrupt is generated, if enabled.
 - b) When the CSCNA bit in the AD1CON2 registers is set to '1', this determines when the ADC analog scan channel list, defined in the AD1CSSL/AD1CSSH registers, starts over from the beginning.
 - c) When the DMA peripheral is not used (ADDMAEN = 0), this determines when the ADC Result Buffer Pointer to ADC1BUF0-ADC1BUFF gets reset back to the beginning at ADC1BUF0.
 - d) When the DMA peripheral is used (ADDMAEN = 1), this determines when the DMA Address Pointer is incremented after a sample/conversion operation. ADC1BUF0 is the only ADC buffer used in this mode. The ADC Result Buffer Pointer to ADC1BUF0-ADC1BUFF gets reset back to the beginning at ADC1BUF0. The DMA address is incremented after completion of every 32nd sample/conversion operation. Conversion results are stored in the ADC1BUF0 register for transfer to RAM using DMA.
- 2. When the DMA module is disabled (ADDMAEN = 0), the ADC has 16 result buffers. ADC conversion results are stored sequentially in ADC1BUF0-ADC1BUFF, regardless of which analog inputs are being used subject to the SMPIx bits and the condition described in 1c) above. There is no relationship between the ANx input being measured and which ADC buffer (ADC1BUF0-ADC1BUFF) that the conversion results will be placed in.
- 3. When the DMA module is enabled (ADDMAEN = 1), the ADC module has only 1 ADC result buffer (i.e., ADC1BUF0) per ADC peripheral and the ADC conversion result must be read, either by the CPU or DMA Controller, before the next ADC conversion is complete to avoid overwriting the previous value.
- 4. The DONE bit (AD1CON1<0>) is only cleared at the start of each conversion and is set at the completion of the conversion, but remains set indefinitely, even through the next sample phase until the next conversion begins. If application code is monitoring the DONE bit in any kind of software loop, the user must consider this behavior because the CPU code execution is faster than the ADC. As a result, in Manual Sample mode, particularly where the user's code is setting the SAMP bit (AD1CON1<1>), the DONE bit should also be cleared by the user application just before setting the SAMP bit.

5. Enabling op amps, comparator inputs and external voltage references can limit the availability of analog inputs (ANx pins). For example, when Op Amp 2 is enabled, the pins for ANO, AN1 and AN2 are used by the op amp's inputs and output. This negates the usefulness of Alternate Input mode since the MUXA selections use AN0-AN2. Carefully study the ADC block diagram to determine the configuration that will best suit your application. Configuration examples are available in the "Analog-to-Digital Converter (ADC)" (DS70621) section in the "dsPIC33/ PIC24 Family Reference Manual".

23.3 ADC Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the
	product page using the link above, enter
	this URL in your browser:
	http://www.microchip.com/wwwproducts/
	Devices.aspx?dDocName=en555464

23.3.1 KEY RESOURCES

- "Analog-to-Digital Converter (ADC)" (DS70621) in the "dsPIC33/PIC24 Family Reference Manual"
- · Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related "dsPIC33/PIC24 Family Reference Manual" Sections
- Development Tools

NOTES:

Base Instr #	Assembly Mnemonic		Assembly Syntax	Description	# of Words	# of Cycles ⁽²⁾	Status Flags Affected
25	DAW	DAW	Wn	Wn = decimal adjust Wn	1	1	С
26	DEC	DEC	f	f = f - 1	1	1	C,DC,N,OV,Z
		DEC	f,WREG	WREG = f – 1	1	1	C,DC,N,OV,Z
		DEC	Ws,Wd	Wd = Ws - 1	1	1	C,DC,N,OV,Z
27	DEC2	DEC2	f	f = f – 2	1	1	C,DC,N,OV,Z
		DEC2	f,WREG	WREG = f – 2	1	1	C,DC,N,OV,Z
		DEC2	Ws,Wd	Wd = Ws - 2	1	1	C,DC,N,OV,Z
28	DISI	DISI	#lit14	Disable Interrupts for k instruction cycles	1	1	None
29	DIV	DIV.S	Wm,Wn	Signed 16/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.SD	Wm,Wn	Signed 32/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.U	Wm,Wn	Unsigned 16/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.UD	Wm,Wn	Unsigned 32/16-bit Integer Divide	1	18	N,Z,C,OV
30	DIVF	DIVF	Wm, Wn ⁽¹⁾	Signed 16/16-bit Fractional Divide	1	18	N,Z,C,OV
31	DO	DO	#lit15,Expr ⁽¹⁾	Do code to PC + Expr, lit15 + 1 times	2	2	None
		DO	Wn, Expr ⁽¹⁾	Do code to PC + Expr, (Wn) + 1 times	2	2	None
32	ED	ED	Wm*Wm,Acc,Wx,Wy,Wxd ⁽¹⁾	Euclidean Distance (no accumulate)	1	1	OA,OB,OAB, SA,SB,SAB
33	EDAC	EDAC	Wm*Wm,Acc,Wx,Wy,Wxd ⁽¹⁾	Euclidean Distance	1	1	OA,OB,OAB, SA,SB,SAB
34	EXCH	EXCH	Wns,Wnd	Swap Wns with Wnd	1	1	None
35	FBCL	FBCL	Ws,Wnd	Find Bit Change from Left (MSb) Side	1	1	С
36	FF1L	FF1L	Ws,Wnd	Find First One from Left (MSb) Side	1	1	С
37	FF1R	FF1R	Ws,Wnd	Find First One from Right (LSb) Side	1	1	С
38	GOTO	GOTO	Expr	Go to address	2	4	None
		GOTO	Wn	Go to indirect	1	4	None
		GOTO.L	Wn	Go to indirect (long address)	1	4	None
39	INC	INC	f	f = f + 1	1	1	C,DC,N,OV,Z
		INC	f,WREG	WREG = f + 1	1	1	C,DC,N,OV,Z
		INC	Ws,Wd	Wd = Ws + 1	1	1	C,DC,N,OV,Z
40	INC2	INC2	f	f = f + 2	1	1	C,DC,N,OV,Z
		INC2	f,WREG	WREG = f + 2	1	1	C,DC,N,OV,Z
		INC2	Ws,Wd	Wd = Ws + 2	1	1	C,DC,N,OV,Z
41	IOR	IOR	f	f = f .IOR. WREG	1	1	N,Z
		IOR	f,WREG	WREG = f.IOR. WREG	1	1	N,Z
		IOR	#lit10,Wn	Wd = lit10 .IOR. Wd	1	1	N,Z
		IOR	Wb,Ws,Wd	Wd = Wb .IOR. Ws	1	1	N,Z
		IOR	Wb,#lit5,Wd	Wd = Wb .IOR. lit5	1	1	N,Z
42	LAC	LAC	Wso,#Slit4,Acc	Load Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
43	LNK	LNK	#lit14	Link Frame Pointer	1	1	SFA
44	LSR	LSR	f	f = Logical Right Shift f	1	1	C,N,OV,Z
		LSR	f,WREG	WREG = Logical Right Shift f	1	1	C,N,OV,Z
		LSR	Ws,Wd	Wd = Logical Right Shift Ws	1	1	C,N,OV,Z
		LSR	Wb,Wns,Wnd	Wnd = Logical Right Shift Wb by Wns	1	1	N,Z
		LSR	Wb,#lit5,Wnd	Wnd = Logical Right Shift Wb by lit5	1	1	N,Z
45	MAC	MAC	Wm*Wn,Acc,Wx,Wxd,Wy,Wyd,AWB ⁽¹⁾	Multiply and Accumulate	1	1	OA,OB,OAB, SA,SB,SAB
		MAC	Wm*Wm,Acc,Wx,Wxd,Wy,Wyd ⁽¹⁾	Square and Accumulate	1	1	OA,OB,OAB, SA,SB,SAB

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.



АС СНА	AC CHARACTERISTICS			rating Co wise state perature	pnditions: 3.0V to 3.6V ed) $-40^{\circ}C \le TA \le +85^{\circ}C$ for Industrial $-40^{\circ}C \le TA \le +125^{\circ}C$ for Extended				
Param No.	Symb	Characteristic	Min.	Тур. ⁽¹⁾	Max.	Units	Conditions		
OS10	FIN	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes)	DC	_	60	MHz	EC		
		Oscillator Crystal Frequency	3.5 10	—	10 25	MHz MHz	XT HS		
OS20	Tosc	Tosc = 1/Fosc	8.33	—	DC	ns	+125°C		
		Tosc = 1/Fosc	7.14	—	DC	ns	+85°C		
OS25	TCY	Instruction Cycle Time ⁽²⁾	16.67	—	DC	ns	+125°C		
		Instruction Cycle Time ⁽²⁾	14.28	—	DC	ns	+85°C		
OS30	TosL, TosH	External Clock in (OSC1) High or Low Time	0.45 x Tosc	—	0.55 x Tosc	ns	EC		
OS31	TosR, TosF	External Clock in (OSC1) Rise or Fall Time	—	—	20	ns	EC		
OS40	TckR	CLKO Rise Time ^(3,4)	—	5.2	—	ns			
OS41	TckF	CLKO Fall Time ^(3,4)	—	5.2	—	ns			
OS42	Gм	External Oscillator Transconductance ⁽⁴⁾	—	12	—	mA/V	HS, VDD = 3.3V, TA = +25°C		
			—	6	—	mA/V	XT, VDD = 3.3V, TA = +25°C		

TABLE 30-17: EXTERNAL CLOCK TIMING REQUIREMENTS

Note 1: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

- 2: Instruction cycle period (TCY) equals two times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "Minimum" values with an external clock applied to the OSC1 pin. When an external clock input is used, the "Maximum" cycle time limit is "DC" (no clock) for all devices.
- 3: Measurements are taken in EC mode. The CLKO signal is measured on the OSC2 pin.
- 4: This parameter is characterized, but not tested in manufacturing.

TABLE 30-39:SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0)TIMING REQUIREMENTS

AC CHARACTERISTICS			$\begin{array}{l} \mbox{Standard Operating Conditions: 3.0V to 3.6V} \\ \mbox{(unless otherwise stated)} \\ \mbox{Operating temperature} & -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for Industrial} \\ & -40^{\circ}C \leq TA \leq +125^{\circ}C \mbox{ for Extended} \end{array}$					
Param.	Symbol	Characteristic ⁽¹⁾	Min.	Typ. ⁽²⁾	Max.	Units	Conditions	
SP70	FscP	Maximum SCK2 Input Frequency			15	MHz	(Note 3)	
SP72	TscF	SCK2 Input Fall Time	—		_	ns	See Parameter DO32 (Note 4)	
SP73	TscR	SCK2 Input Rise Time	—		_	ns	See Parameter DO31 (Note 4)	
SP30	TdoF	SDO2 Data Output Fall Time	—		—	ns	See Parameter DO32 (Note 4)	
SP31	TdoR	SDO2 Data Output Rise Time	—		_	ns	See Parameter DO31 (Note 4)	
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns		
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	_	_	ns		
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	_	_	ns		
SP41	TscH2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30		_	ns		
SP50	TssL2scH, TssL2scL	$\overline{SS2}$ ↓ to SCK2 ↑ or SCK2 ↓ Input	120		_	ns		
SP51	TssH2doZ	SS2 ↑ to SDO2 Output High-Impedance	10	_	50	ns	(Note 4)	
SP52	TscH2ssH TscL2ssH	SS2 ↑ after SCK2 Edge	1.5 Tcy + 40	_	_	ns	(Note 4)	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 66.7 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.





TABLE 30-44:SPI1 MASTER MODE (FULL-DUPLEX, CKE = 0, CKP = x, SMP = 1)TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \le TA \le +85^{\circ}C$ for Industrial $-40^{\circ}C \le TA \le +125^{\circ}C$ for Extended					
Param.	Symbol	Characteristic ⁽¹⁾	Min. Typ. ⁽²⁾ Max. Units Condition					
SP10	FscP	Maximum SCK1 Frequency	_	—	10	MHz	-40°C to +125°C (Note 3)	
SP20	TscF	SCK1 Output Fall Time	_	—	—	ns	See Parameter DO32 (Note 4)	
SP21	TscR	SCK1 Output Rise Time	_	—	—	ns	See Parameter DO31 (Note 4)	
SP30	TdoF	SDO1 Data Output Fall Time	_	—	—	ns	See Parameter DO32 (Note 4)	
SP31	TdoR	SDO1 Data Output Rise Time	_	—	—	ns	See Parameter DO31 (Note 4)	
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	_	6	20	ns		
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	_	_	ns		
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	_	_	ns		
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30			ns		

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

- **3:** The minimum clock period for SCK1 is 100 ns. The clock generated in Master mode must not violate this specification.
- 4: Assumes 50 pF load on all SPI1 pins.



FIGURE 30-27: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING CHARACTERISTICS

NOTES:

28-Lead Plastic Quad Flat, No Lead Package (MM) - 6x6x0.9mm Body [QFN-S] With 0.40 mm Terminal Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	MILLIMETERS				
Dimension	Limits	MIN	NOM	MAX	
Number of Pins	Ν	28			
Pitch	е	0.65 BSC			
Overall Height	А	0.80	0.90	1.00	
Standoff	A1	0.00	0.02	0.05	
Terminal Thickness	A3	0.20 REF			
Overall Width	Е	6.00 BSC			
Exposed Pad Width	E2	3.65	3.70	4.70	
Overall Length	D	6.00 BSC			
Exposed Pad Length	D2	3.65	3.70	4.70	
Terminal Width	b	0.23	0.30	0.35	
Terminal Length	L	0.30	0.40	0.50	
Terminal-to-Exposed Pad	K	0.20	-	-	

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

2. Package is saw singulated

3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

 $\label{eq:REF:Reference Dimension, usually without tolerance, for information purposes only.$

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48-Lead Ultra Thin Plastic Quad Flat, No Lead Package (MV) - 6x6 mm Body [UQFN] With 0.40 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	MILLIMETERS			
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.40 BSC		
Optional Center Pad Width	W2			4.45
Optional Center Pad Length	T2			4.45
Contact Pad Spacing	C1		6.00	
Contact Pad Spacing	C2		6.00	
Contact Pad Width (X28)	X1			0.20
Contact Pad Length (X28)	Y1			0.80
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2153A